MC13-LE3

Server Motherboard - microATX UP





AMD RYZEN

Features

- AMD EPYC™ 4004 Series Processors
- AMD Ryzen[™] 9000 / Ryzen[™] 7000 Series Processors
- · Single processor, Socket AM5
- Dual Channel DDR5 ECC/Non-ECC UDIMM, 4 DIMMs
- 2 x 25Gb/s LAN ports via Broadcom® BCM57502
- 2 x 1Gb/s LAN ports via Intel® I210-AT
- 1 x MCIO 8i connector with PCIe Gen5 x8 interface
- 4 x SATA 6Gb/s ports
- 1 x M.2 slot with PCIe Gen5 x4 interface
- 1 x PCle Gen5 x16 expansion slot
- 1 x PCle Gen4 x4 expansion slot
- ASPEED® AST2600 Baseboard Management Controller

Specification

Form Factor	microATX (W244 x D244 mm)	Rear I/O	2 x USB 3.2 Gen1, 1 x VGA, 1 x COM, 2 x SFP28, 2 x RJ45, 1 x MLAN
CPU	AMD EPYC [™] 4004 Series Processors AMD Ryzen [™] 9000 Series Processors AMD Ryzen [™] 7000 Series Processors Single processor, TDP up to 170W	ТРМ	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010
Socket	1 x AM5	PSU Connectors	1 x 24-pin ATX main power connector 1 x 8-pin ATX 12V power connector
Chipset	AMD B650E	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	4 x DIMM slots, 2-channel memory architecture DDR5 UDIMM memory supported Ryzen 9000: Up to 5600 MT/s (1DPC), 3600 MT/s (2DPC) EPYC 4004 / Ryzen 7000: 5200 MT/s (1DPC), 3600 MT/s (2DPC)	OS Compatibility	EPYC 4004 Series: Ubuntu 22.04 / Ubuntu 24.04 Windows Server 2022
LAN	2 x 25Gb/s LAN (1 x Broadcom® BCM57502) 2 x 1Gb/s LAN (2 x Intel® I210-AT) - Support NCSI 1 x 10/100/1000 management LAN		Ryzen 9000/7000 Series: Windows 10 21H2 / Windows 11
		Operating Properties	Operating temperature: 10°C to 40°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C
Video	Integrated in ASPEED® AST2600 - 1 x VGA port		
Storage Interface	1 x MCIO 8i for 2 x Gen5 NVMe, from CPU, shared with Slot_3 4 x SATA 7-pin, from FCH 1 x M.2 (2242/2280), PCIe Gen5 x4, from CPU		Non-operating humidity: 20%-95% (non-condensing)
		Retail Packaging Content	1 x MC13-LE3, 1 x I/O shield, 1 x Quick start guide, 4 x SATA 6Gb/s cables (500mm) Single Box dimensions: 321 x 308.5 x 78.5 mm Carton dimensions: 630 x 420 x 345 mm
RAID	RAID 0/1/10		
Expansion	Slot_3: PCle x16 (Gen5 x16), from CPU, shared with MClO Slot_1: PCle x4 (Gen4 x4), from FCH		Quantity: 10 x single boxes in one carton
Slots		Bulk Packaging	20 x MC13-LE3, 20 x I/O shields
Internal I/O	1 x CPU fan header, 5 x System fan headers, 1 x USB 2.0 port, 1 x USB 3.2 Gen1 x2 header, 1 x USB 2.0 x2 header, 4 x SATA connectors, 1 x Front panel header, 1 x Backplane board header, 1 x PMBUS connector, 1 x IPMB connector, 1 x TPM header	Content	Carton dimensions: 609 x 581 x 362 mm
		Reference Numbers	Retail: 9MC13LE3MR-000-1* Bulk: 9MC13LE3NR-000-1*



Learn more at https://www.GIGABYTE.com/enterprise

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